## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Yasunori INOUE et al.

Serial No.: 08/921,250

Filed: August 29, 1997

For: FABRICATION METHOD OF SEMICONDUCTOR DEVICE AND

ABRASIVE LIQUID USED THEREIN

Examiner: George GOUDREAU

Group Art Unit: 1765

Date: November 9, 1999

## RESPONSE TO THE RESTRICTION REQUIREMENT DATED OCTOBER 27, 1999

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

This paper is submitted in response to the Official Action dated October 27, 1999.

In the Action, restriction is required between Group (I), claims 1 - 28 drawn to a method for cmp polishing semiconductor substrate; and Group (II), claims 29 - 30 drawn to a cmp polishing composition.

Applicants hereby elect the subject matter of Group (I), claims 1 - 28 for prosecution in this application. This election is made without traverse, it being understood that the applicants' rights to the filing of a Divisional application directed to the non-elected subject matter under 35 USC §120 and 35 USC §121 are retained.

In the event that this paper is not timely filed, applicants hereby petition for an appropriate extension of time. The fee for any such extension may be charged to our Deposit Account No. 01-2340.

In the event any additional fees are required in connection with this response, please charge our Deposit Account No. 01-2340.

Respectfully submitted,

ARMSTRONG, WESTERMAN, HATTORI, McLELAND & NAUGHTON

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